Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size .004” X .004”**

**Backside Potential:**

**Mask Ref: H24**

**APPROVED BY: DK DIE SIZE .074” X .087” DATE: 6/16/22**

**MFG: ANALOG DEVICES THICKNESS .020” P/N: ADG508AB**

**DG 10.1.2**

#### Rev B, 7/19/02